



DSAF00100L

Silicon PNP epitaxial planar type

For general amplification

Complementary to DSCF001

DSA3001 in ML3 type package

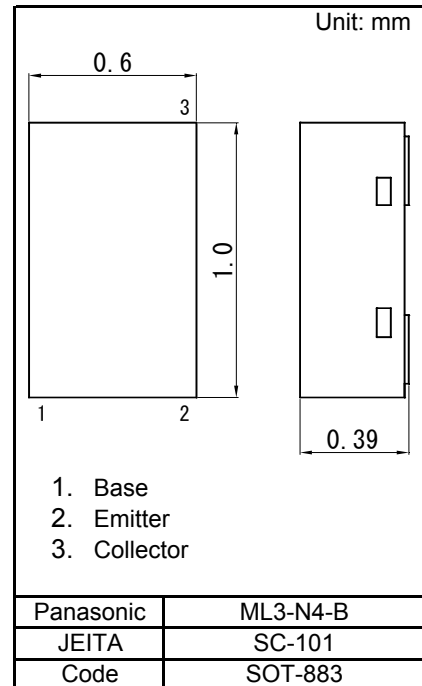
■ Features

- High forward current transfer ratio hFE with excellent linearity
- Low collector-emitter saturation voltage Vce(sat)
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: A1

■ Packaging

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	-60	V
Collector-emitter voltage (Base open)	VCEO	-50	V
Emitter-base voltage (Collector open)	VEBO	-7	V
Collector current	IC	-100	mA
Peak collector current	ICp	-200	mA
Collector power dissipation ^{*1}	Pc	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

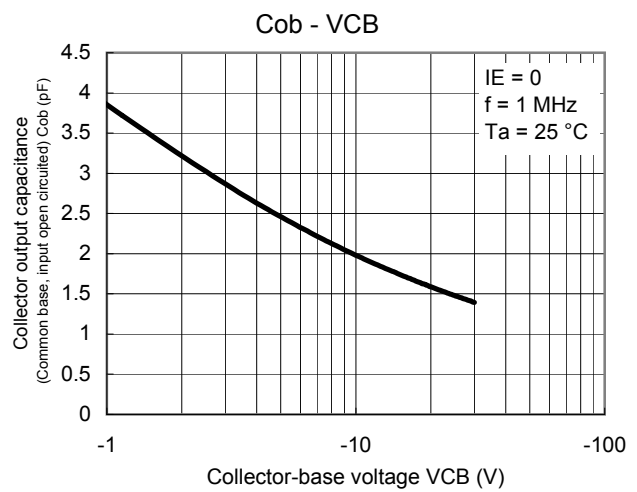
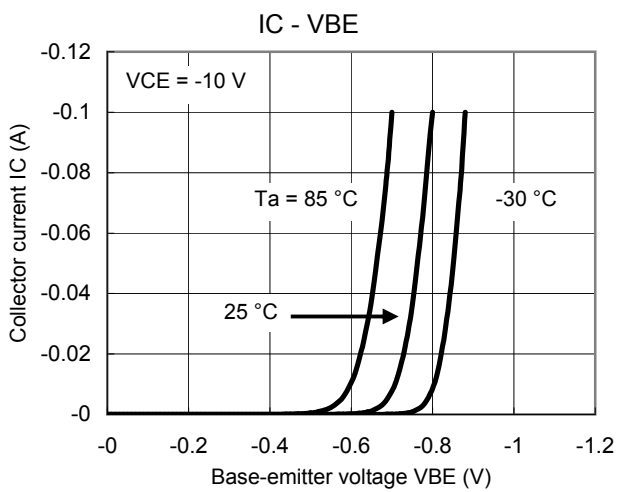
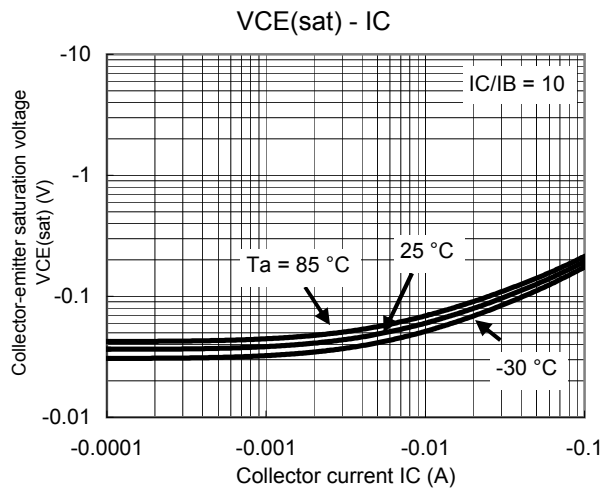
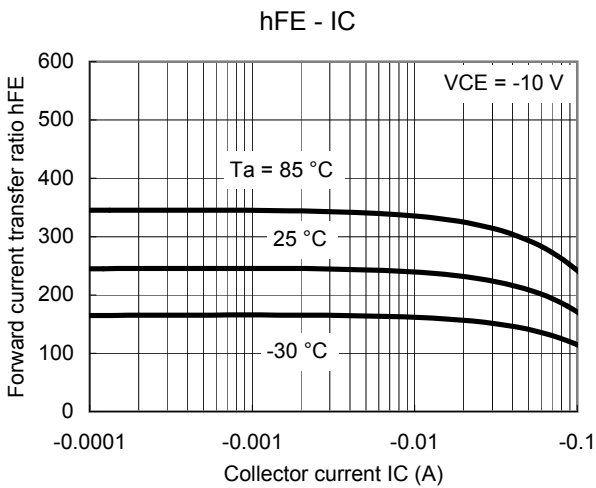
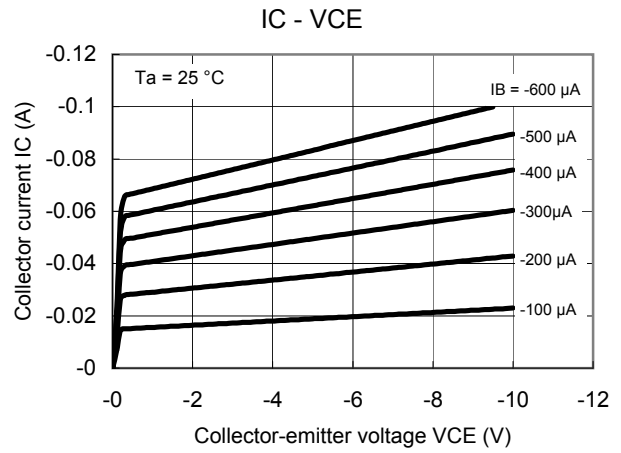
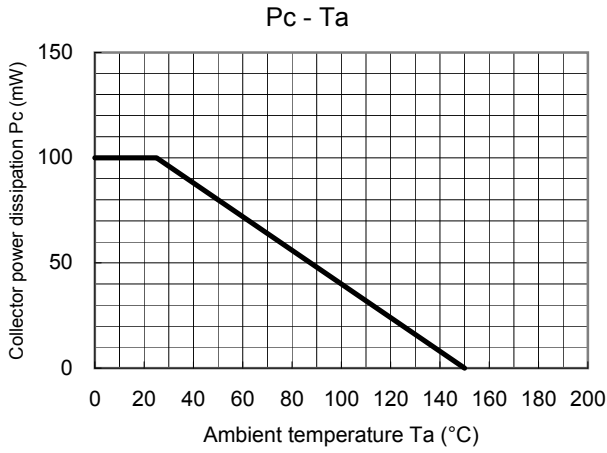
Note) *1: Copper plate at the collector is 5.0 mm² on substrate at 10 x 12 x 0.8t mm.

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = -10 μA, IE = 0	-60			V
Collector-emitter voltage (Base open)	VCEO	IC = -2 mA, IB = 0	-50			V
Emitter-base voltage (Collector open)	VEBO	IE = -10 μA, IC = 0	-7			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = -20 V, IE = 0			-0.1	μA
Collector-Emitter cutoff current (base open)	ICEO	VCE = -10 V, IB = 0			-100	μA
Forward current transfer ratio ^{*1}	hFE	VCE = -10 V, IC = -2mA	210		460	-
Collector-emitter saturation voltage	VCE(sat)	IC = -100 mA, IB = -10 mA		-0.2	-0.5	V
Transition frequency	fT	VCE = -10 V, IC = -2 mA		150		MHz
Collector output capacitance (Common base, input open circuited)	Cob	VCB = -10 V, IE = 0, f = 1 MHz		2		pF

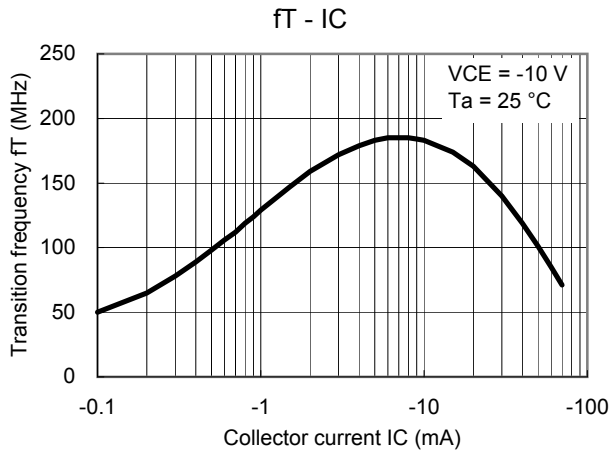
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

Technical Data (reference)





Technical Data (reference)



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